

# Engineering Report

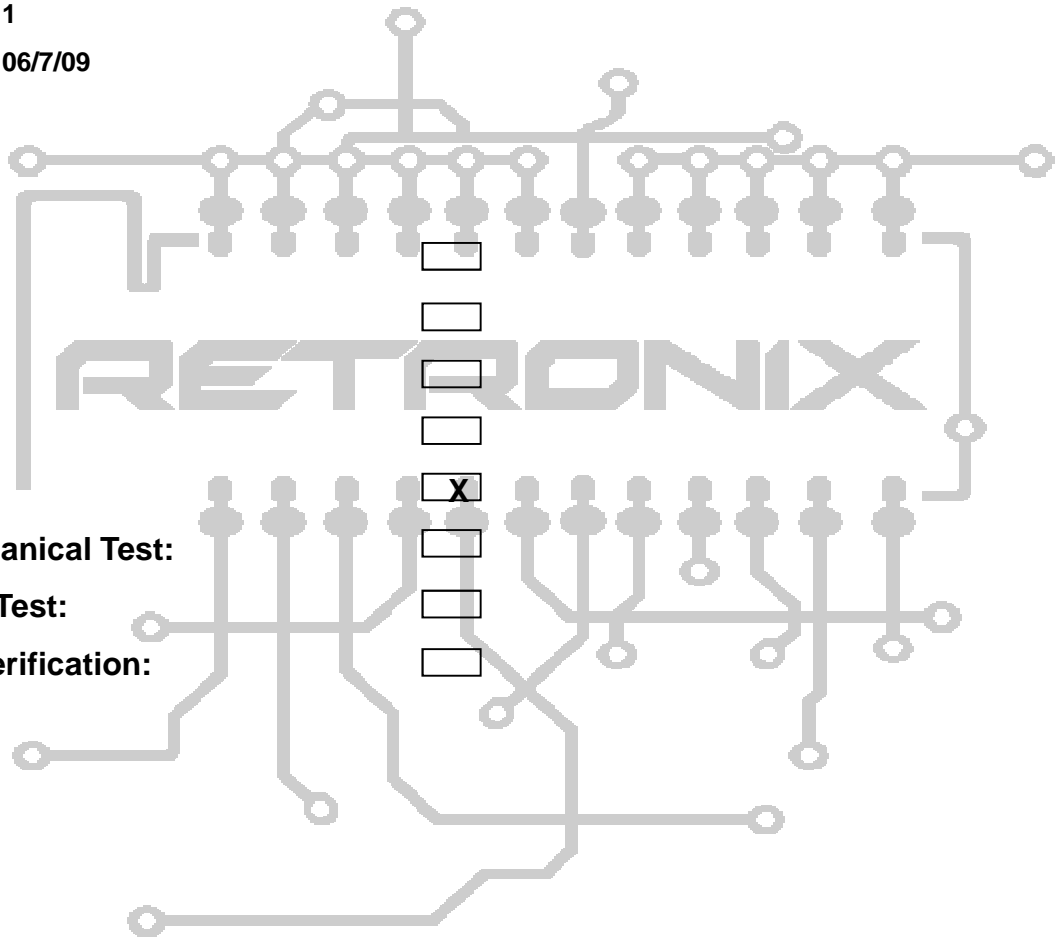
Ret. No.

Eng 006

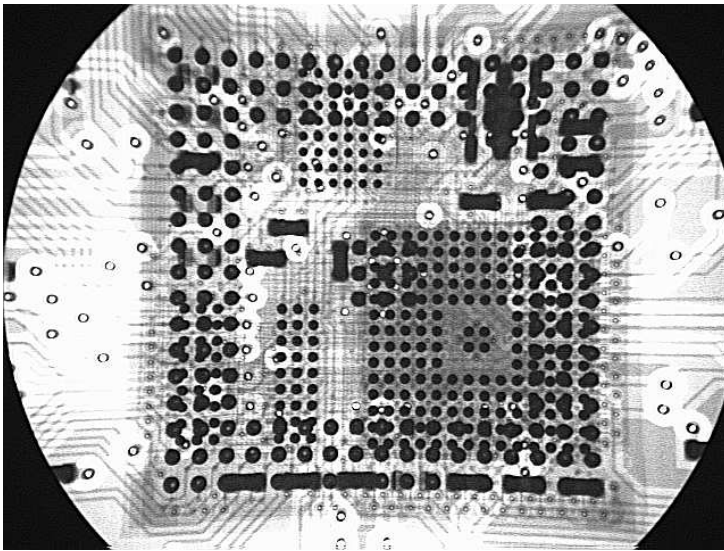
**Customer:** GOOD ONE  
**PO No:** 137331  
**Device:** PCB  
**BRF:** 11621  
**QTY:** 1  
**Date:** 06/7/09

**Test:**   
**Bga repair:**   
**Pcb Repair:**   
**XRF:**   
**X-Ray:**

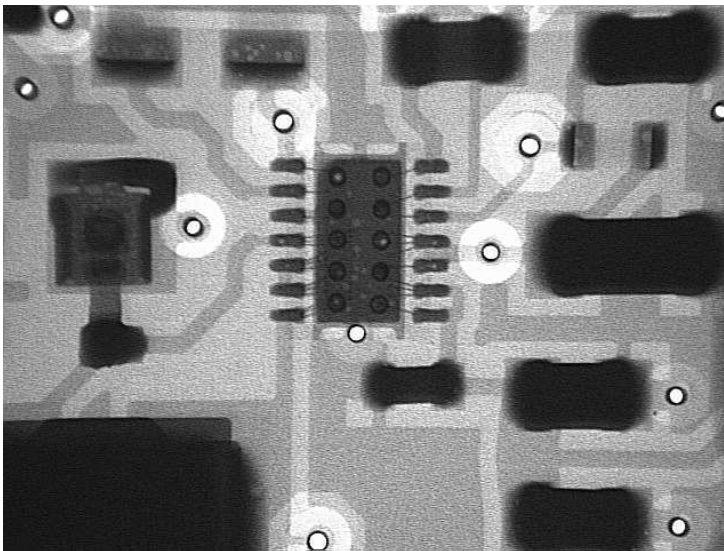
**Optical Mechanical Test:**   
**Solderability Test:**   
**Inspection/verification:**



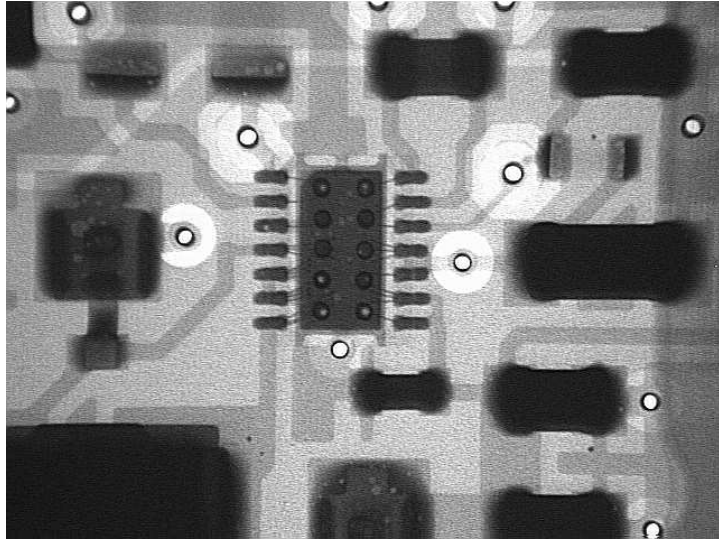
X-Ray results :-



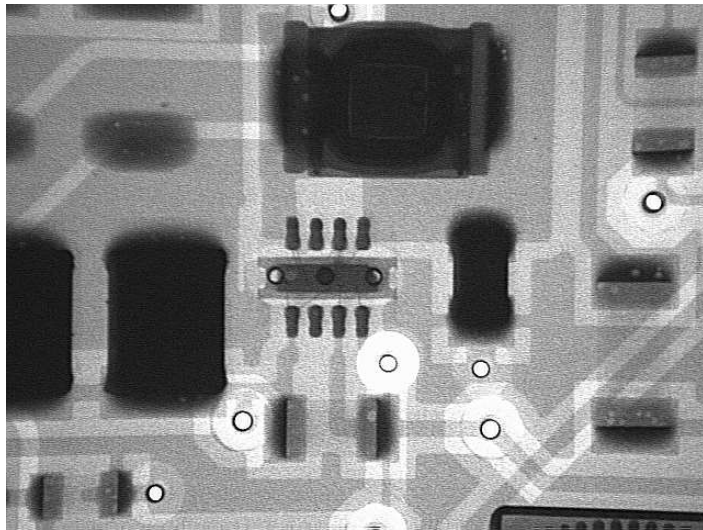
IC1



IC24



IC25



IC29

It was found that IC 1 was a POP. The X-ray image shows that voids are present in the spheres connecting the POP to the PCB. However, they are <25% by area so would not be cause for rejection in line with IPC 610 level 3.

No further anomalies found on the other devices within the POP. IC24, IC25 and IC29 all Ok.